TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (Ultra-High-Speed U-MOS III)

TPC8022-H

High-Efficiency DC/DC Converter Applications
Notebook PC Applications
Portable-Equipment Applications
CCFL Inverter Applications

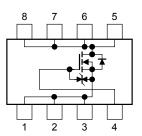
- Small footprint due to a small and thin package
- High speed switching
- Small gate charge: QSW = 3.5 nC (typ.)
- Low drain-source ON-resistance: R_{DS} (ON) = 22 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 15 \text{ S (typ.)}$
- Low leakage current: IDSS = 10 μA (max) (VDS = 40 V)
- Enhancement mode: $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic			Symbol	Rating	Unit
Drain-source vol	tage		V_{DSS}	40	V
Drain-gate voltage (R _{GS} = 20 kΩ)			V_{DGR}	40	V
Gate-source vol	age		V_{GSS}	±20	V
5	DC	(Note 1)	I _D	7.5	Α
Drain current	Pulse	(Note 1)	I _{DP}	V _{GSS} ±20 I _D 7.5	A
Drain power diss (t = 10 s)	sipation	(Note 2a)	P _D	1.9	W
Drain power dissipation (t = 10 s) (Note 2b)			P _D	1.0	W
Single-pulse avalanche energy (Note 3)			E _{AS}	26	mJ
Avalanche current			I _{AR}	7.5	Α
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 4)			Ear	0.08	mJ
Channel temperature			T _{ch}	150	°C
Storage temperature range			T _{stg}	-55 to 150	°C

Weight: 0.085 g (typ.)

Circuit Configuration



Note: For Notes 1 to 4, refer to the next page.

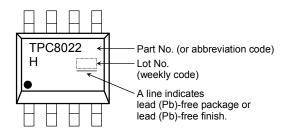
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	C/VV

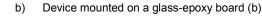
Marking (Note 5)

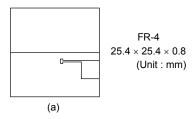


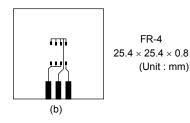
Note 1: The channel temperature should not exceed 150°C during use.

Note 2:

Device mounted on a glass-epoxy board (a)





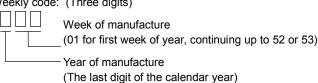


Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 0.5 mH, R_G = 25 Ω , I_{AR} = 7.5 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: • on the lower left of the marking indicates Pin 1.

* Weekly code: (Three digits)



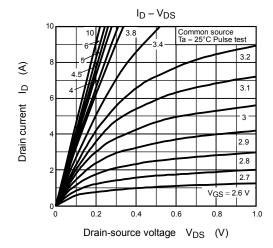
Electrical Characteristics (Ta = 25°C)

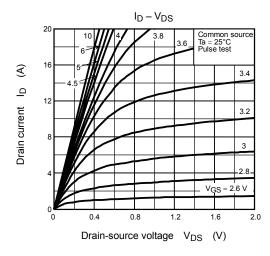
Chara	Characteristic		Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	_	_	10	μΑ
Drain-source breakdown voltage		V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	40	_	_	V
		V (BR) DSX	I _D = 10 mA, V _{GS} = -20 V		_	_	v
Gate threshold v	oltage/	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.1	_	2.3	V
Drain-source O	N-resistance	R _{DS (ON)}	V _{GS} = 4.5 V, I _D = 3.8 A		27	35	mΩ
Drain-source ON-resistance Forward transfer admittance		R _{DS} (ON)	V _{GS} = 10 V, I _D = 3.8 A	_	22	27	11122
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 3.8 A	7.5	15	I	S
Input capacitano	e	C _{iss}		1	650	1	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	1	55	I	pF
Output capacitance		Coss		1	240	1	
Switching time	Rise time	tr	$V_{GS} \stackrel{10}{\overset{\circ}{\circ}} V \stackrel{I_{D}}{\overset{\circ}{\circ}} = 3.8 \text{ A}$ $V_{GS} \stackrel{10}{\overset{\circ}{\circ}} V \stackrel{I_{D}}{\overset{\circ}{\circ}} = 3.8 \text{ A}$ $V_{DD} \stackrel{\circ}{\overset{\circ}{\circ}} V \stackrel{\circ}{$	_	3	_	ns
	Turn-on time	t _{on}		l	9	ı	
	Fall time	t _f		1	2		
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \mu s$	l	18	l	
	Total gate charge (gate-source		$V_{DD} \approx 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$	_	11	_	
plus gate-drain)		Qg	$V_{DD} \approx 32 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 7.5 \text{ A}$	_	6.2	_	
Gate-source charge		Q _{gs1}	$V_{DD} \approx 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$	_	2.1	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	2.7	_	-
Gate switching charge		Q _{sw}		_	3.5	_	

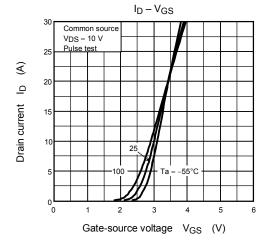
Source-Drain Ratings and Characteristics (Ta = 25°C)

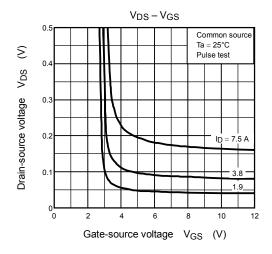
Charact	eristic	Symbol	Test Condition	Min	Тур.	Тур. Мах	
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	30	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 7.5 A, V _{GS} = 0 V	_	_	-1.2	V

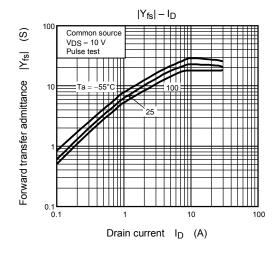
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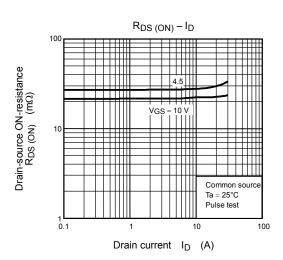




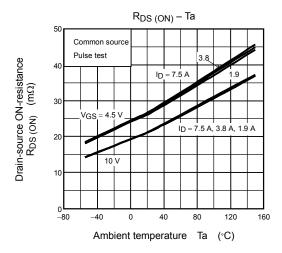


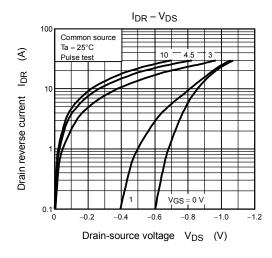


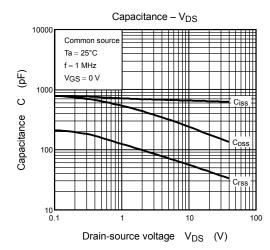


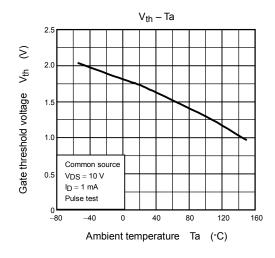


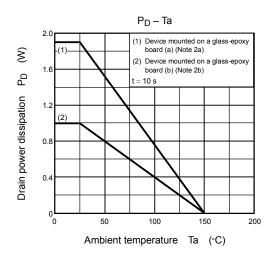
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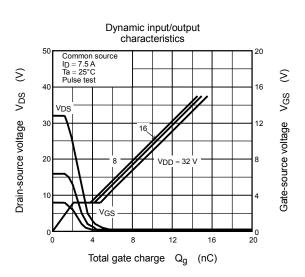


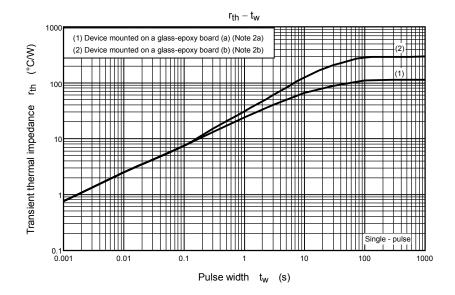


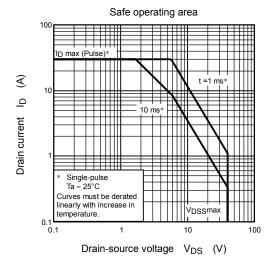












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